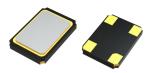


#### **FEATURE**

- Size 5.0×3.2, thickness 0.9mm
- High precision and high frequency stability
- Excellent heat resistance and environmental characteristics
- Designed for automatic mounting and reflow soldering
- RoHS Compliant / Pb Free



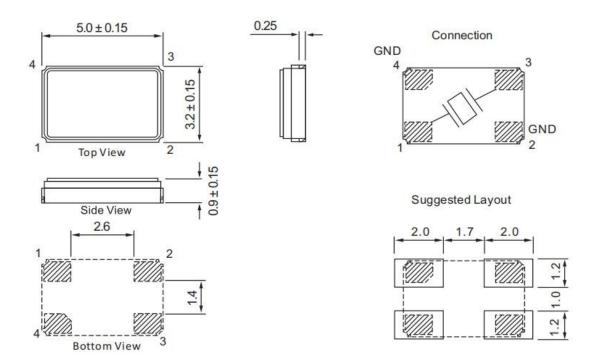
# $\mathbf{1}_{_{\sim}}$ ELECTRICAL SPECIFICATIONS

	,
Hold Style	5032 Seam
Nominal Frequency	12.00000MHz
Mode	Fundamental / AT
Frequency Tolerance (at 25°C)	±10ppm
Frequency Stability Over Operating Temperature Characteristics	±50ppm
Operating Temperature Range	-40°C ~ +85 °C
Storage Temperature Range	-55℃ ~ +125 ℃
Shunt Capacitance (C <sub>0</sub> )	5.0pF Max
Driver Level (Typical)	100μW
Load Capacitance(C <sub>L</sub> )	8pF
ESR	45Ω Max
Insulation Resistance	More than 500Mohms at DC100V
Aging @25°C 1 <sup>st</sup> year (Max)	±3ppm/year

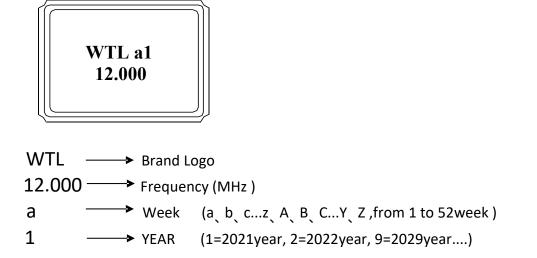
REMARK: SPECIFICATIONS SUBJECT TO CHANGE WITHOUT PRIOR NOTICE. PLEASE CONFIRM WITH OUR SALES ENGINEER.



### 2 DIMENSIONS (Unit: mm)



# 3 MARKING

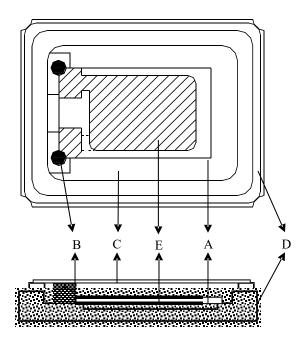


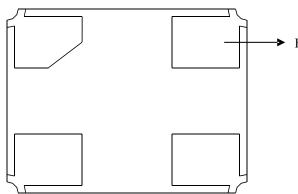
#### Marking Instruction:

The date code was marked on the crystal body, which will be easily traced back in case of quality issue.



# $\mathbf{4}_{_{\sim}}$ STRUCTURE ILLUSTRATION





	Parts Material		QTY	COLOR
Α	Blank	Mostly SiO2	1	White
В	Conductive paste	Ag:80%, silicone resin 10%	2	Greyish
С	Lid	Fe:52~56%,Ni:16~18%,Co:28~30%	1	Silvery
D	Package	Ceramic		Brown
E	Plating(blank)	Ag:99.99%		Silvery
F	Pad	Cu:6.6%,Au:0.2%,Fe:56%,Ni:18%	4	Golden

### Series TX5, P/N: WTL5M36960PZ SMD Seam Sealed Crystals 5.0×3.2 mm

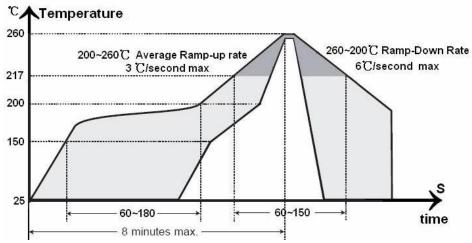


## **5** RELIABILITY SPECIFICATIONS

Item	Conditions	Result
Low Temp.	Put the crystal into the -40 $^{\circ}\mathrm{C}$ ±2 $^{\circ}\mathrm{C}$ constant temperature box for	∆F≦±5 PPM
Storage	500±2 H , Measurement taken after 2 hour.	△RR≦±5 ohms
High Temp. Storage	Put the crystal into the +100°C±2°C constant temperature box for	ΔF≦±5 PPM
	500±2 H, Measurement taken after 2 hour.	∆RR≦±5 ohms
High Temp &	Put the crystal into the constant temperature & humid with the	∆F≦±5 PPM
Humidity	temperatures 85 $^{\circ}$ C ±3 $^{\circ}$ C and the humidity 98% for 500±2 H.	△RR≦±5 ohms
	Measurement taken after 2 hour.	
Thermal Shock	Put the crystal into the constant temperature-55 $^{\circ}$ C ±2 $^{\circ}$ C for	∆F≦±5 PPM
	30±1M, then change the temperature to +85 $^{\circ}$ C±2 $^{\circ}$ C for 30±1M,	∆RR≦±5 ohms
	the total is 100times. Measurement taken after 2 hour.	
Resistance To	Passed through the re-flow oven under the following condition.	∆F≦±5 PPM
Soldering Heat	Preheat to 150°C±5°C for 60 to 120sec, and peak 265°C±5°C for	△RR≦±5 ohms
	10s±3sec. Measurement taken after DUT being left at room temperature for at 24±2 hours	
Drop Test	The crystal fall off the cement floor with the height 100cm±5cm	ΔF≦±5 PPM
	for 3 times. Measurement taken after 2 hour.	△RR≦±5 ohms
Vibration Test	Apply 0.75mm vibration at sweep frequency 10 ~ 500 Hz, for 2h.	∆F≦±5 PPM
	10 cycles in each direction of 3 axis. Measurement taken after 2 hour.	∆RR≦±5 ohms
Shock	Peak 1000m/s2, normal width 6ms half sine wave form, 3.7m/s, 3	ΔF≦±5 PPM
	perpendicular axis of samples, 3 cycles / direction, total 18 cycles. Measurement taken after 2 hour.	∆RR≦±5 ohms
Fine Leak	Helium Bombing 4.5kgf/cm2 for 2 hr	Less than 1*10^-
	3 3 7 3 7 2 2 3 1	8atm.c.c./sec,
		Helium
Solder ability	In 245 $\pm$ 5 $^{\circ}$ C solder bath for 2 $\pm$ 0.5 seconds. 8-12X magnifier.	Terminals shall be
		covered more then 95% with solder.
		55/0 WILLI SUIUEL.



## **6** SUGGESTED REFLOW PROFILE



Peak temperature.  $260^{\circ}C \pm 5^{\circ}C$  (10sec. max.)

#### **7 SUBSTANCES IN PRODUCT**

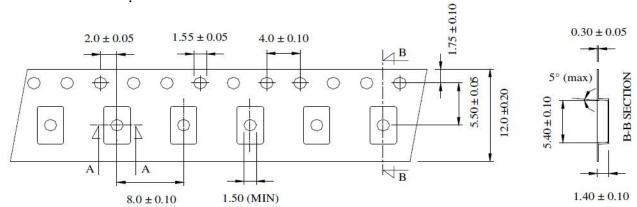
Drawing number	Disassembly Unit/component description	Homogeneous Material Name.	Substance Name	CAS No.	Substance Mass. (mg)	Content Rate(%)per
	Crystal blank	Quartz	SiO <sub>2</sub>	14808-60-7	1.0131	100.00%
	Electrode	Electrode-Ag	Ag	7440-22-4	0.2332	100.00%
	Package	Ceramics	Al <sub>2</sub> O <sub>3</sub>	1344-28-1	32.6582	90.00%
			$Mn_2O_3$	1317-34-6	1.4515	4.00%
			SiO <sub>2</sub>	7631-86-9	1.4515	4.00%
			MoO <sub>3</sub>	1313-27-5	0.3629	1.00%
			MgO	1309-48-4	0.3629	1.00%
		Kovar ring	Fe	7439-89-6	0.4227	53.00%
			Ni	7440-02-0	0.2313	29.00%
			Со	7440-48-4	0.1436	18.00%
		Plate	Au	7440-57-5	0.2273	19.00%
SMD5032			Ni	7440-02-0	0.9690	81.00%
		Metallizing	Мо	7439-98-7	0.3988	100.00%
		Solder	Ag	7440-22-4	0.8494	71.00%
			Cu	7440-50-8	0.3469	29.00%
	Lid	Kovar	Fe	7439-89-6	13.5809	48.50%
			Ni	7440-02-0	9.8006	35.00%
			Со	7440-48-4	4.4803	16.00%
			Mn	7439-96-5	0.1400	0.50%
1	Conduct Adhesive	siliver adhesive	Ag	7440-22-4	0.6134	70.00%
			Pd	7440-05-3	0.0438	5.00%
			C <sub>11</sub> H <sub>24</sub>	1120-21-4	0.0876	10.00%
			C <sub>12</sub> H <sub>26</sub>	112-40-3	0.0438	5.00%
			SiO <sub>2</sub>	7631-86-9	0.0876	10.00%

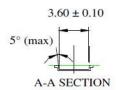
All the products we provide meet the requirements of RoHS and Reach regulations, and we send SGS for ICP test every year.



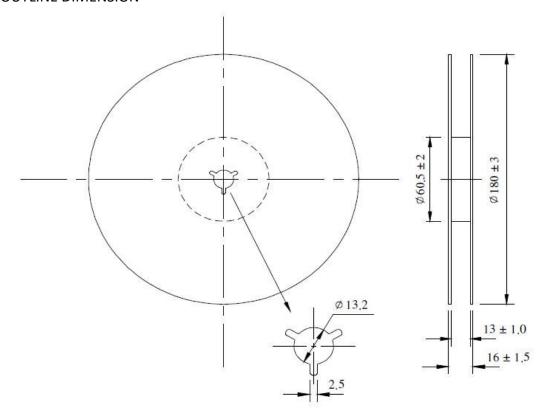
## **8 PACKING SPECIFICATIONS (Unit: mm)**

TAPE SPECIFICATION:





#### **OUTLINE DIMENSION**



Q'ty: 1000pcs/Reel



# $\mathbf{9}_{_{\sim}}$ WTL PART NUMBER SYSTEM :

For example: WTL5M25835PZ

[Instructions: for project management, WTL will trace back the part number to developer wherever it goes]

WTL. Brand

**5M**: Package Code

**<u>25835</u>**: Serial number , flow code , without any rules

PZ: WTL Developer Code, for example: VH,CH,PZ,RZ,ML